



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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TIC 1000A

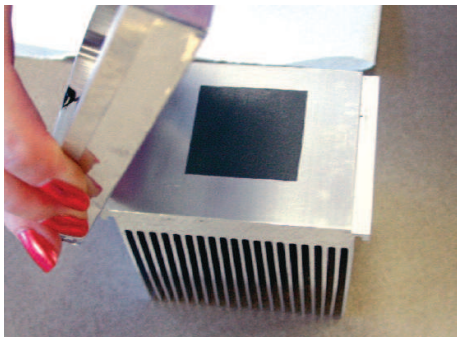
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PRODUCT DESCRIPTION

High Performance, Value Compound for High-End Computer Processors

FEATURES AND BENEFITS

- High thermal performance: 0.32°C/W (@ 50 psi)
- Good screenability
- Room temperature storage
- No post “cure” required
- Exceptional value



TIC™ 1000A is a high performance, thermally conductive compound intended for use as a thermal interface material between a highend computer processor and a heat sink. Other high watt density applications will also benefit from the extremely low thermal impedance of TIC™ 1000A.

The TIC™ 1000A compound wets-out the thermal interface surfaces and flows to produce the lowest thermal impedance. The compound requires pressure of the assembly to cause flow. The TIC™ 1000A compound will resist dripping.

For microprocessor applications, traditional screw fastening or spring clamping methods will provide adequate force to optimize the thermal performance of TIC™ 1000A.

An optimized application would utilize the minimum volume of TIC™ 1000A material necessary to ensure complete wet-out of both mechanical interfaces.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF TIC 1000A

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD			
Color	Gray	Gray	Visual			
Density (g/cc)	2.1	2.1	ASTM D792			
Continuous Use Temp (°F) / (°C)	302	150	—			
ELECTRICAL						
Electrical Resistivity (Ohm-meter) (1)	N/A	N/A	ASTM D257			
THERMAL						
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470			
THERMAL PERFORMANCE vs PRESSURE						
	Pressure (psi)	10	25	50	100	200
	TO-220 Thermal Performance (°C/W) (2)	0.32	0.32	0.32	0.31	0.28

1) The compound contains an electrically conductive filler surrounded by electrically non-conductive resin.
2) TO-220 performance data is provided as a reference to compare material thermal performance.

Assembly – No Post Screen Cure

TIC™ 1000A has good screenability. No solvent is used to reduce the viscosity, so no post “cure” conditioning is required.

Application Cleanliness

1. Pre-clean heat sink and component interface with isopropyl alcohol prior to assembly or repair. Ensure heat sink is dry before applying TIC™ 1000A.

Application Methods

1. Dispense and/or screenprint TIC™ 1000A compound onto the processor or heat sink surface like thermal grease (see a Bergquist Representative for application information).
2. Assemble the processor and heat sink with spring clips or constant-pressure fasteners.

TYPICAL APPLICATIONS INCLUDE

- High performance CPUs and GPUs

Disclaimer

Note:

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Reference 0.1